

AMENDMENTS TO THE CLAIMS

A listing of all claims and their current status in accordance with 37 C.F.R. § 1.121(c) is provided below.

1-13. (Canceled)

14. (Original) A device comprising:

a chip; and

a package operatively coupled to the chip, the package comprising:

a die side;

a ball side configured to receive a plurality of conductive balls;

a plurality of first non-metal mateable alignment features on the die
side of the package; and

a plurality of second non-metal mateable alignment features on the
~~second~~ ball side of the package.

15. (Original) The device, as set forth in claim 14, wherein the package comprises a molded resin body.

16. (Original) The device, as set forth in claim 14, wherein the plurality of first mateable alignment features are male and the plurality of second mateable alignment features are female.

17. (Original) The device, as set forth in claim 14, wherein the plurality of first mateable alignment features are male and the plurality of second mateable alignment features are male.

18. (Original) The device, as set forth in claim 14, wherein the plurality of first mateable alignment features are female and the plurality of second mateable alignment features are male.

19. (Original) The device, as set forth in claim 14, wherein the plurality of first mateable alignment features are female and the plurality of second mateable alignment features are female.

20. (Original) The device, as set forth in claim 14, wherein the chip comprises a memory chip.

21. (Original) The device, as set forth in claim 14, wherein the plurality of first mateable alignment features and the plurality of second mateable alignment features are arranged asymmetrically.

22. (Original) A package comprising:
a die side configured to receive a die;
a ball side configured to receive a plurality of conductive balls;

a plurality of first non-metal mateable alignment features on the die side of
the package; and
a plurality of second non-metal mateable alignment features on the ball side
of the package.

23. (Original) The package, as set forth in claim 22, wherein the package
comprises a molded resin body.

24. (Original) The package, as set forth in claim 22, wherein the plurality of
first mateable alignment features are male and the plurality of second mateable alignment
features are female.

25. (Original) The package, as set forth in claim 22, wherein the plurality of
first mateable alignment features are male and the plurality of second mateable alignment
features are male.

26. (Original) The package, as set forth in claim 22, wherein the plurality of
first mateable alignment features are female and the plurality of second mateable alignment
features are male.

27. (Original) The package, as set forth in claim 22, wherein the plurality of
first mateable alignment features are female and the plurality of second mateable alignment
features are female.

28. (Original) The package, as set forth in claim 22, wherein the plurality of first mateable alignment features and the plurality of second mateable alignment features orient adjacent packages in a unique location.

29. (Original) The package, as set forth in claim 28, wherein the plurality of first mateable alignment features and the plurality of second mateable alignment features are arranged asymmetrically.

30. (Original) The package, as set forth in claim 28, wherein the plurality of first mateable alignment features and the plurality of second mateable alignment features comprising of at least one unique alignment feature.

31. (Original) The package, as set forth in claim 22, wherein the plurality of first mateable alignment features and the plurality of second mateable alignment features support adjacent packages during solder ball reflow.

32. (Original) The package, as set forth in claim 22, wherein the plurality of first mateable alignment features and the plurality of second mateable alignment features are arranged asymmetrically.